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(54) Title: LEAD-FREE EUTECTIC SOLDER ALLOY COMPRISING ZINC AS THE MAIN COMPONENT AND ALUMINUM AS AN ALLOYING METAL

(57) Abstract: Lead-free solder alloy comprising zinc (Zn) as the main component and aluminum (Al) as an alloying metal, wherein the solder alloy is a eutectic having a single melting point in the range of 320 to 390 °C (measured by DSC at a heating rate of 5 °C min⁻¹).

